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(12) **United States Design Patent** (10) **Patent No.:** **US D505,122 S**
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(54) **PORTION OF A MATRIX FOR SURFACE MOUNT PACKAGE LEADFRAME**
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(*) Notice: This patent is subject to a terminal disclaimer.
(**) Term: **14 Years**
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(51) **LOC (7) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Search** D13/182; 29/622, 29/827; 174/52.2, 52.4, 260; 206/713, 714, 715, 716, 727, 728; 257/667, 668, 666, 670, 686, 692; 333/185; 428/573

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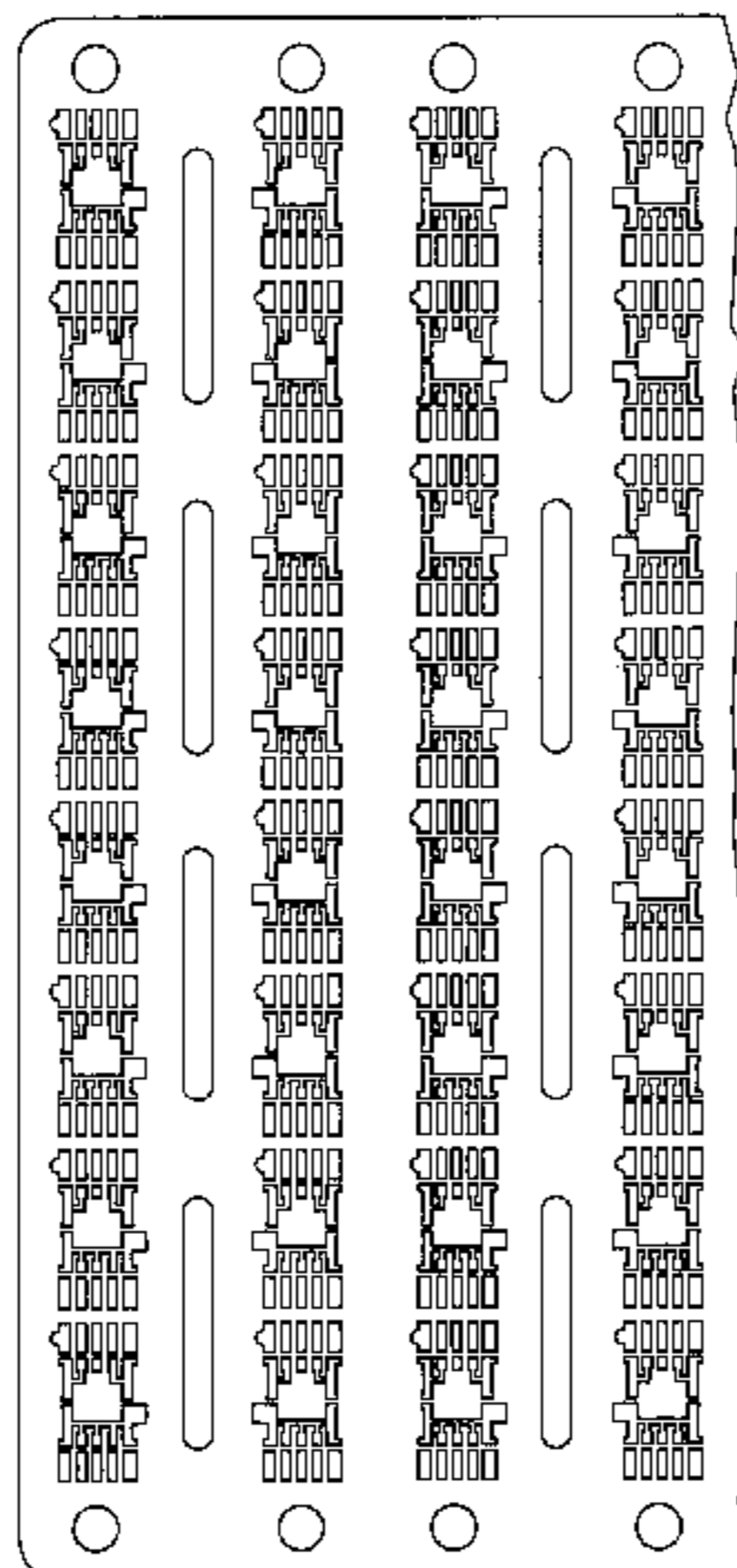
(57) **CLAIM**

The ornamental design for portion of a matrix for surface mount package leadframe, as shown and described.

DESCRIPTION

FIG. 1 is a top plan view of a portion of a matrix for surface mount package leadframes showing my new design;
FIG. 2 is a top plan view of an enlarged fragment of the portion of a matrix for surface mount package leadframe; and,
FIG. 3 is a perspective view of a matrix for surface mount package leadframes showing my new design.

1 Claim, 3 Drawing Sheets



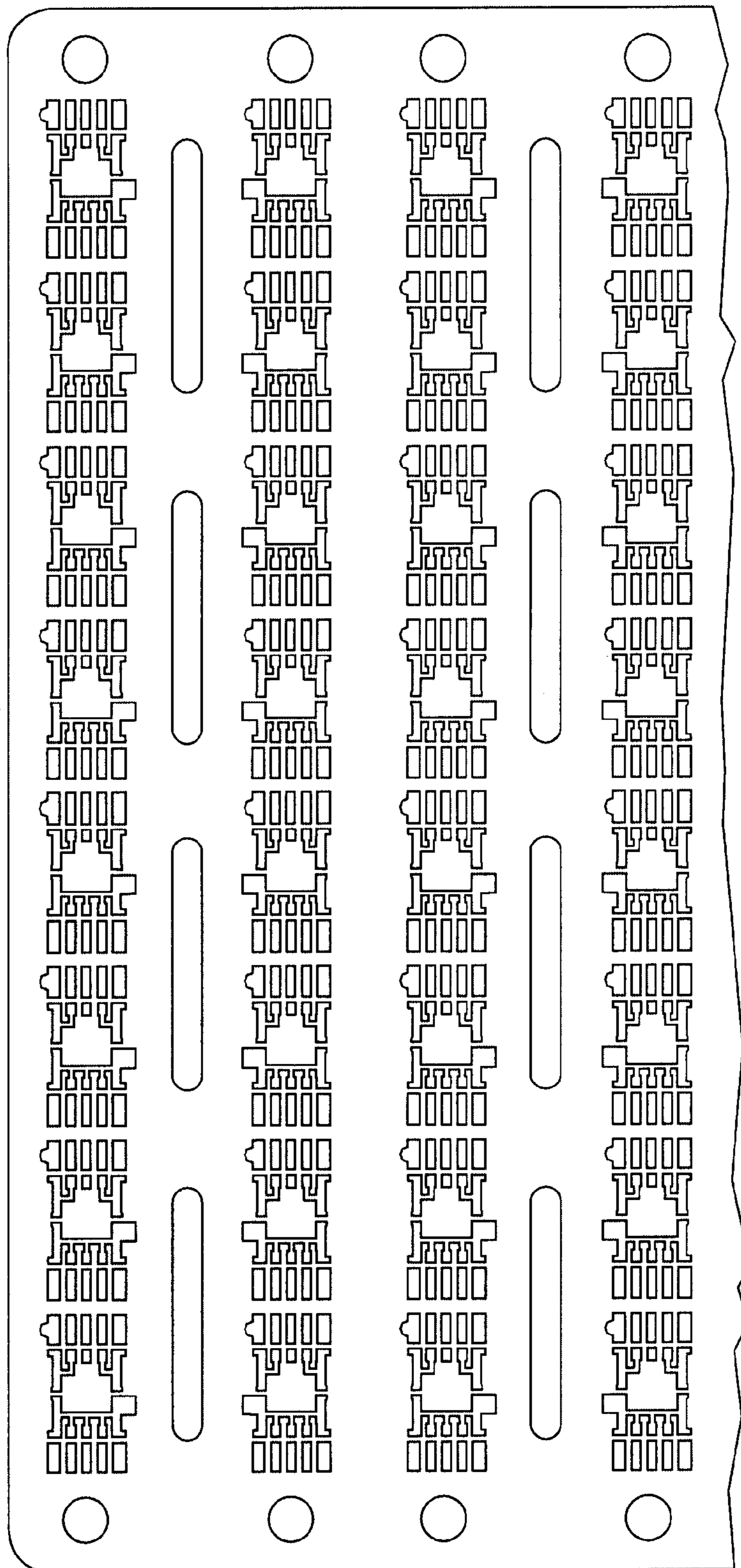


FIG. 1

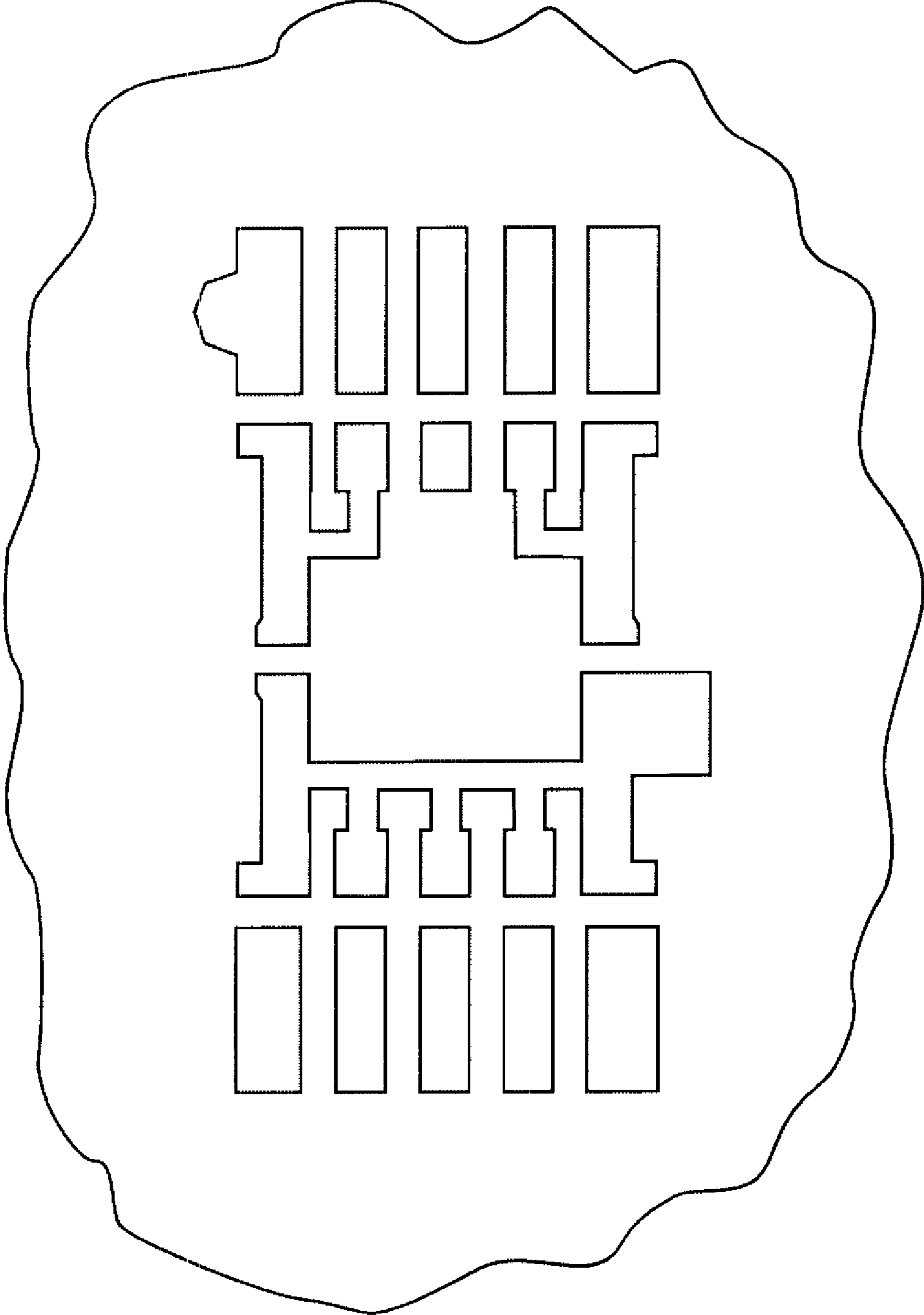


FIG. 2

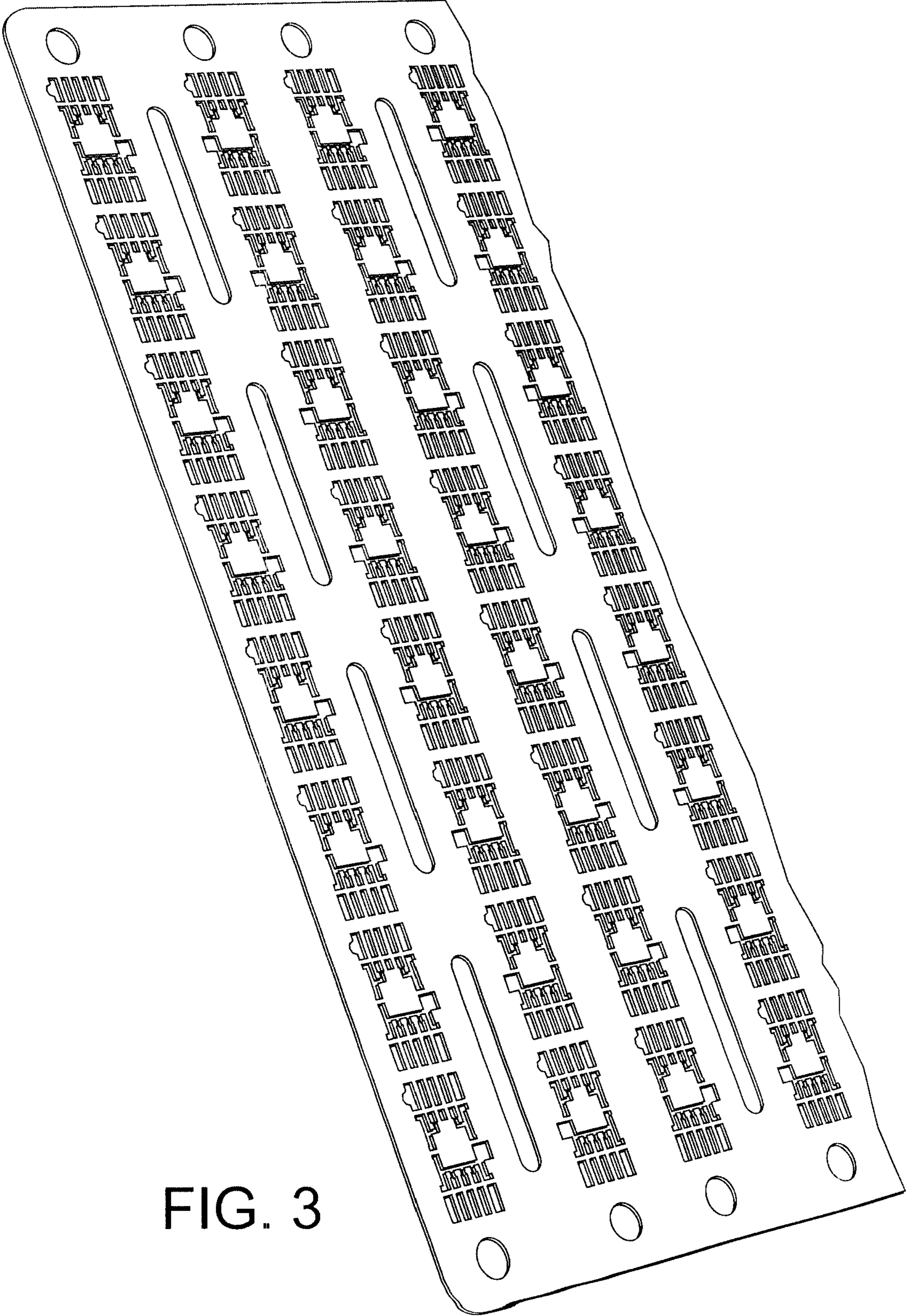


FIG. 3